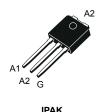


4 A - Triac in IPAK package



Features

- 4 A Triac
- V_{DRM} / V_{RRM} = 600 V and V_{DSM} / V_{RSM} = 750 V
- 125 °C maximum junction temperature T_j
- IPAK package
- 4 quadrants triacs with I_{GT} = 25 mA
- · Halogen-free molding, lead-free plating
- ECOPACK2 compliant

Applications

- Actuators
- Heating elements
- Inrush current limiting circuits

Product summary I_{T(RMS)} 4 A V_{DSM}/V_{RSM} 750 V I_{GT} 25 mA T_i max. 125 °C

Product status link

Z0410MH

Description

The Z0410MH series is 4 A Triac housed in compact through-hole IPAK package. This 4 quadrants device is suited to home appliances or power tools and industrial systems and drives loads up to 4 A.



1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value	Unit	
I _{T(RMS)}	RMS on-state current (full sine wave) T _c = 107 °C		4	Α
l	Non repetitive surge peak on-state current (full cycle,	t = 16.7 ms	16	Α
I _{TSM}	T _j initial = 25 °C)	t = 20 ms	15	A
l ² t	I ² t value for fusing	t _p = 10 ms	1.5	A ² s
dl/dt	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$, tr ≤ 100 ns, f = 120 Hz		50	A/µs
V _{DRM} /V _{RRM}	Repetitive peak off-state voltage T _j = 125 °C		600	V
V _{DSM} /V _{RSM}	Non Repetitive peak off-state voltage, 10 ms	750	V	
I _{GM}	Maximum peak gate current $t_p = 20 \mu s$, $T_i = 125 ^{\circ} \text{C}$		1.2	Α
P _{GM}	Maximum gate power dissipation	0.5	W	
T _{stg}	Storage temperature range	-40 to +125	°C	
Tj	Operating junction temperature range	-40 to +125	°C	
TL	Maximum lead temperature for soldering during 10 s	260	°C	

Table 2. Electrical characteristics (T_j = 25 °C, unless otherwise specified)

Symbol	Test conditions	Value	Unit		
I _{GT} ⁽¹⁾	$V_D = 12 \text{ V}, R_L = 33 \Omega$		Max.	25	mA
V _{GT}	$V_D = 12 \text{ V}, R_L = 33 \Omega$		Max.	1.3	V
V _{GD}	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega$ $T_j = 125 ^{\circ}\text{C}$		Min.	0.2	V
IL	I _G = 1.2 x I _{GT}	I-III-IV	Max.	25	mA
1 <u>G</u> - 1.2 × 1 <u>G</u>	IG - 1.2 × IG	II	Max.	50	mA
I _H ⁽²⁾	I _T = 500 mA, gate open		Max.	25	mA
dV/dt (2)	V_D = 67 % V_{DRM} ; V_R = 67 % V_{RRM} , gate open T_j = 110 °C		Min.	200	V/µs
(dV/dt)c (2)	$(dI/dt)c = 1.8 \text{ A/ms}$ $T_j = 110 ^{\circ}\text{C}$		Min.	5	V/µs

^{1.} For both polarities of OUT pin referenced to COM pin.

Table 3. Static characteristics

Symbol	Test conditions T _j			Value	Unit
V _{TM} ⁽¹⁾	$I_{TM} = 5.5 \text{ A}, t_p = 380 \ \mu\text{s}$	25 °C	Max.	2	V
V _{TO} ⁽¹⁾	Threshold voltage	125 °C	Max.	0.95	V
R _D ⁽¹⁾	Dynamic resistance	125 °C	Max.	180	mΩ
I _{DRM} /I _{RRM}	$V_D = V_R = V_{DRM} = V_{RRM}$	25 °C	Max.	5	μΑ
יטאשייRRM		125°C		0.5	mA

^{1.} For both polarities of A2 referenced to A1.

DS14061 - Rev 1 page 2/10

^{2.} For both polarities of A2 referenced to A1.



Table 4. Thermal resistance

Symbol	Parameter	Value	Unit	
R _{th(j-c)}	Junction to case (AC)	Max.	3	°C/W
R _{th(j-a)}	Junction to ambient	Тур.	70	°C/W

DS14061 - Rev 1 page 3/10



Characteristics (curves) 1.1

RMS current (full cycle) P(W) α=180 °

Figure 1. Maximum power dissipation versus on-state

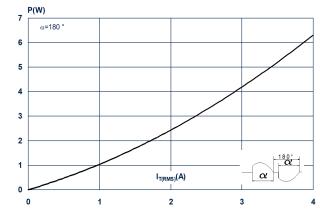


Figure 2. Average and DC on-state current versus case temperature I_{T(RMS)}(A)

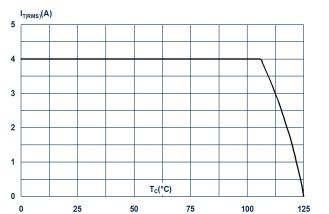


Figure 3. On-state RMS current versus ambient temperature (full cycle)

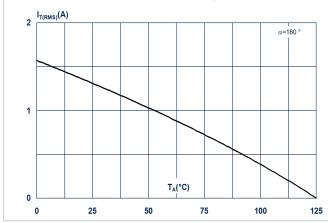


Figure 4. Relative variation of thermal impedance versus pulse duration

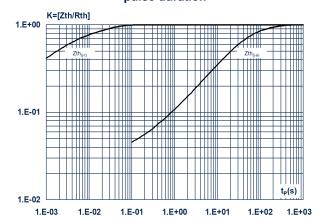


Figure 5. Relative variation of gate triggering current and voltage versus junction temperature (typical values)

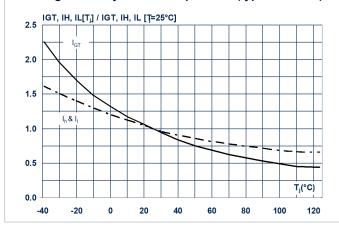
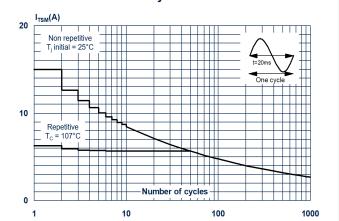


Figure 6. Surge peak on-state current versus number of cycles



DS14061 - Rev 1 page 4/10



Figure 7. Non repetitive surge peak on-state current for a sinusoidal pulse with width $t_{\rm p}$ < 10 ms and corresponding value of l^2t

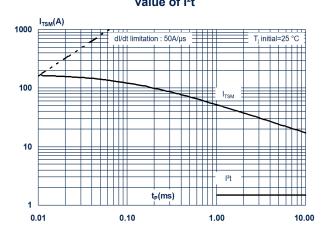


Figure 8. On-state characteristics (maximum values)

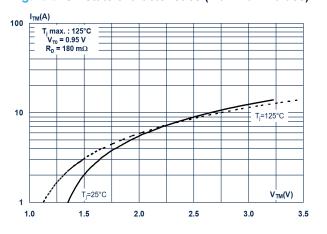


Figure 9. Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values)

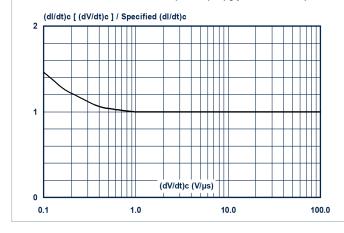


Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature

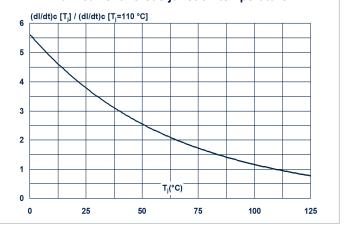
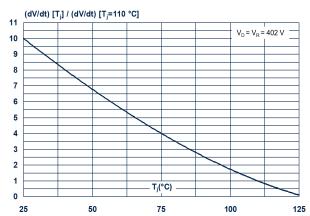


Figure 11. Relative variation of static dV/dt immunity versus junction temperature



DS14061 - Rev 1 page 5/10



2 Ordering information

Figure 12. Ordering information scheme

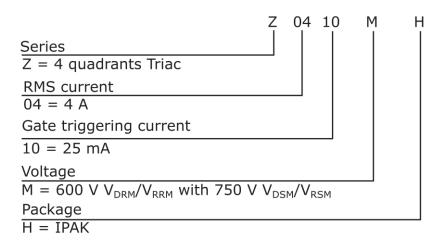


Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
Z0410MH	Z0410MH	IPAK	0.31 g	75	Tube

DS14061 - Rev 1 page 6/10



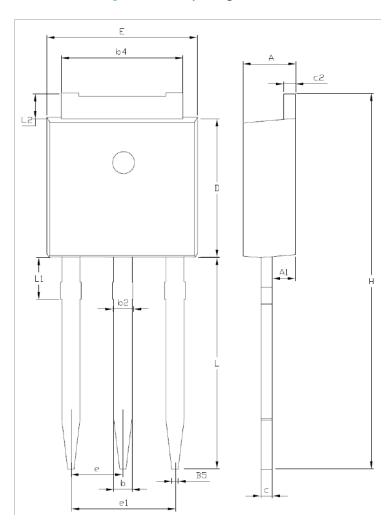
3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 IPAK package information

- Molding compouned resin is halogen free and meets UL94 flammability standard, level V0
- · Lead-free package leads plating

Figure 13. IPAK package outline



DS14061 - Rev 1 page 7/10



Table 6. IPAK package mechanical data

	Dimensions					
Ref.	MillimetersInches (for reference only)					
	Min.	Тур.	Max.	Min.	Тур.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10			0.035
b	0.64		0.90	0.025		0.035
b2			0.95			0.037
b4	5.20		5.43			
B5		0.30			0.012	
С	0.45		0.60			
c2	0.46		0.60			
D	6		6.20			
Е	6.40		6.65	0.252		0.262
е		2.28			0.090	
e1	4.40		4.60	0.173		0.181
Н		16.10			0.634	
L	9		9.60	0.354		0.377
L1	0.8		1.20	0.031		0.047
L2		0.80	1.25		0.031	0.049
V1		10°			10°	

DS14061 - Rev 1 page 8/10



Revision history

Table 7. Document revision history

Date	Revision	Changes
05-Sep-2022	1	Initial release.

DS14061 - Rev 1 page 9/10



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DS14061 - Rev 1 page 10/10

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